



Product Change Notification

106897 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Japan Email: jccb.ijkk@intel.com

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Product Change Notification

Change Notification #: 106897 - 00
Change Title: Intel NetStructure® IXB28504XGBE, IXB28504XGBEFS, PCN 106897-00, Product Design, Convert to a more current Intel Flash Memory device, add washer to board handle, change EMI gasket alignment, and component changes in the DC/DC converter circuit
Date of Publication: November 15, 2006

Key Characteristics of the Change:

Product Design

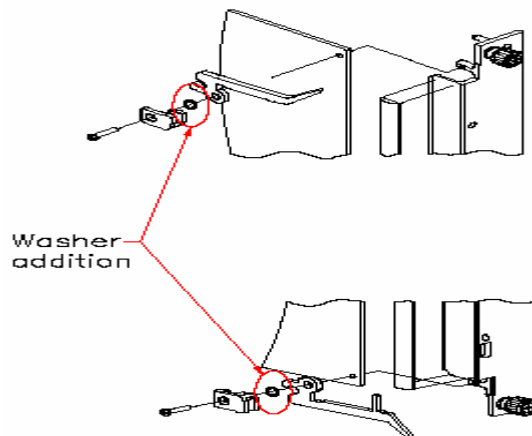
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 30, 2006
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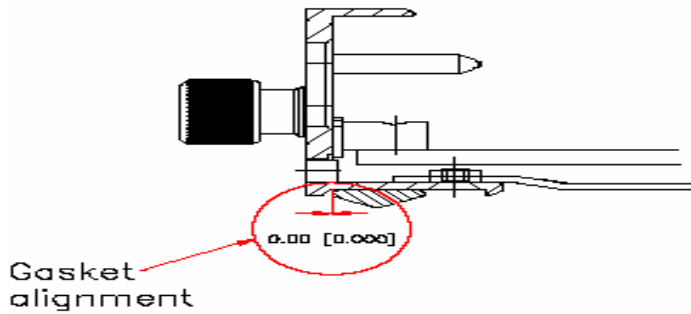
Description of Change to the Customer:

The following four changes are being made:

1. Implement a more current version of Intel 32Mb flash memory device. The new version is a lithography conversion from a 180nm process to a 130nm process. This new device meets all Intel's quality and reliability standards and is backward compatible with the 180nm device. Refer to PCN 105488-00.
2. Add washers to board handle to enhance retention force of the handle. Location of washers is as shown:



3. The EMI gasket is being moved by 1 mm to be in alignment with the front panel edge and thus avoid the possible interference with installation of the mezzanine board assembly. Location of the gasket is as shown below.



4. To improve the performance of the DC to DC converter circuit the following circuit changes are being made:
- remove inductor L10 and replace with a 1m ohm resistor
 - change C45 from 47pf to 82pf

Customer Impact of Change and Recommended Action:

Intel has evaluated these changes to ensure that they do not have any negative functional implications to our customers. No customer action anticipated.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change CA	Post Change TA	Post Change CA
IXB28504XGBEFS	870497	D16719-007	D16720-007	D16719-008	D16720-008
IXB28504XGBE	870523	D16984-007	D16985-007	D16984-008	D16985-008

Reference Documents / Attachments:

Document: _____ Location #: _____

PCN Revision History:

Date of Revision: November 15, 2006	Revision Number: 00	Reason: Originally Published PCN
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